

## **Initial Information Data Sheet**

### **Inventor Information**

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**Application Information**

Title Line One:: **METHODS FOR FILLING HIGH ASPECT RATIO  
TRENCHES IN SEMICONDUCTOR LAYERS**  
Title Line Two::  
Total Drawing Sheets:: **4**  
Formal Drawings?:: **Yes**  
Application Type:: **Utility**  
Docket Number:: **MIO 0109 PA/02-1541**

**Representative Information**

Registration Number One:: **26,397**  
Registration Number Two:: **27,262**  
Registration Number Three:: **29,001**  
Registration Number Four:: **39,564**  
Registration Number Five:: **38,769**  
Registration Number Six:: **33,758**  
Registration Number Seven:: **42,695**  
Registration Number Eight:: **46,867**  
Registration Number Nine:: **46,506**  
Registration Number Ten:: **46,458**  
Registration Number Eleven:: **52,364**  
Registration Number Twelve:: **30,871**  
Registration Number Thirteen:: **38,086**